

SOT1133-2

plastic compatible thermal enhanced extremely thin quad flat package; no leads; 60 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HXQFN60U
Package type industry code	HXQFN60U
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	22-8-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.95	-	5	5.05	mm
E	package width	4.95	-	5	5.05	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
A ₂	package height	0.38	-	0.4	0.42	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	60	-	

2. Package outline

Fig. 1. Package outline HXQFN60U (SOT1133-2)



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3. Legal information

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